

| <b>L<br/>Number</b> | <b>Hits</b> | <b>Search Text</b>  | <b>DB</b>  | <b>Time stamp</b>           |
|---------------------|-------------|---|--|-----------------------------|
| <b>1</b>            | <b>3</b>    | <b>("5369299").PN.</b>  | <b>USPAT;<br/>US-P PUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:01</b> |
| <b>8</b>            | <b>3</b>    | <b>("5916944").PN.</b>  | <b>USPAT;<br/>US-PGPUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>14:24</b> |
| <b>15</b>           | <b>3</b>    | <b>("4756977").PN.</b>  | <b>USPAT;<br/>US-PGPUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:26</b> |
| <b>22</b>           | <b>1</b>    | <b>("0745811").PN.</b>  | <b>USPAT;<br/>US-PGPUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:27</b> |
| <b>29</b>           | <b>0</b>    | <b>("745811.ap.").PN.</b>   | <b>USPAT;<br/>US-PGPUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:28</b> |
| <b>36</b>           | <b>0</b>    | <b>("745811.AP.").PN.</b>   | <b>USPAT;<br/>US-PGPUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:29</b> |
| <b>43</b>           | <b>18</b>   | <b>"integrated circuit device" and<br/>"encapsulation packaging"</b>  | <b>USPAT;<br/>US-PGPUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:39</b> |
| <b>50</b>           | <b>1</b>    | <b>"light\$ensitive device"</b>                                       | <b>USPAT;<br/>US-PGPUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:40</b> |
| <b>57</b>           | <b>1534</b> | <b>"light sensitive device"</b>                                       | <b>USPAT;<br/>US-PGPUB;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:41</b> |
| <b>64</b>           | <b>790</b>  | <b>"light sensitive device" and (semiconductor<br/>or electronic)</b> | <b>USPAT;<br/>US-PGPUB;<br/>EP ; JPO;<br/>DERWENT;<br/>IBM TDB</b> | <b>2001/12/04<br/>15:42</b> |

|     |     |  |   |                     |
|-----|-----|--|---|---------------------|
| 71  | 338 | ("light sensitive device" and (semiconductor or electronic)) and data  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2001/12/04<br>15:42 |
| 85  | 0   | ((("light sensitive device" and (semiconductor or electronic)) and data) and (coating or protection)) and filler | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2001/12/04<br>15:44 |
| 92  | 27  | ((("light sensitive device" and (semiconductor or electronic)) and data) and (coating or protection)) and matrix | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2001/12/04<br>15:47 |
| 78  | 79  | ("light sensitive device" and (semiconductor or electronic)) and data) and (coating or protection)               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2001/12/04<br>15:49 |
| 106 | 0   | ((("light sensitive device" and (semiconductor or electronic)) and data) and (coating or protection)) and filler | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2001/12/04<br>15:49 |
| 113 | 2   | "light sensitive device" and "reverse engineering"   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2001/12/04<br>15:50 |

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DBs: USPAT, US:PGPUB, EPO, JPO, DERWENT, IBM

☒ Highlight all hit terms initially

**257/922**

Image Text

|   | U                        | I                        | Document ID       | Pages | Title   | Current | Current X                         | Inventor                                  |
|---|--------------------------|--------------------------|-------------------|-------|---|---------|-----------------------------------|---|
| 1 | <input type="checkbox"/> | <input type="checkbox"/> | US 20010033012 A1 | 37    | Anti tamper encapsulation for an integrated circuit     |         |                                   | Kommerling, Oliver<br>; Kommerling, Fritz |
| 2 | <input type="checkbox"/> | <input type="checkbox"/> | US 6201296 B1     | 4     | Semiconductor chip with protection against analyzing    | 257/679 | 257/531<br>; 257/787<br>; 257/788 | Fries, Manfred<br>; et al.                |
| 3 | <input type="checkbox"/> | <input type="checkbox"/> | US 6144106 A      | 7     | Electronic coatings                                     | 257/789 | 257/790<br>; 257/922              | Bearinger, Clayton<br>; et al.            |
| 4 | <input type="checkbox"/> | <input type="checkbox"/> | US 6060773 A      | 12    | Semiconductor chip and method of manufacturing the same | 257/679 | 257/922                           | Ban, Hiroshi<br>; et al.                  |
| 5 | <input type="checkbox"/> | <input type="checkbox"/> | US 5998858 A      | 14    | Microcircuit with memory                                | 257/678 | 257/704                           | Little, Wendell L.                        |

